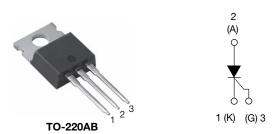


VS-25TTS...PbF Series, VS-25TTS...-M3 Series

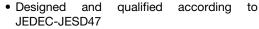
Vishay Semiconductors

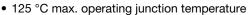
Thyristor High Voltage, Phase Control SCR, 25 A



PRODUCT SUMMARY				
Package	TO-220AB			
Diode variation	Single SCR			
I _{T(AV)}	16 A			
V_{DRM}/V_{RRM}	800 V, 1200 V			
V_{TM}	1.25 V			
I _{GT}	45 mA			
T_J	- 40 °C to 125 °C			

FEATURES





Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912





ROHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

 Typical usage is in input rectification crowbar (soft start) and AC switch in motor control, UPS, welding, and battery charge.

DESCRIPTION

The VS-25TTS... high voltage series of silicon controlled rectifiers are specifically designed for medium power switching and phase control applications. The glass passivation technology used has reliable operation up to 125 °C junction temperature.

OUTPUT CURRENT IN TYPICAL APPLICATIONS					
APPLICATIONS SINGLE-PHASE BRIDGE THREE-PHASE BRIDGE UNITS					
Capacitive input filter $T_A = 55$ °C, $T_J = 125$ °C, common heatsink of 1 °C/W	18	22	Α		

MAJOR RATINGS AND CHARACTERISTICS						
PARAMETER	TEST CONDITIONS	VALUES	UNITS			
I _{T(AV)}	Sinusoidal waveform	16	٨			
I _{RMS}		25	A			
V _{RRM} /V _{DRM}		800/1200	V			
I _{TSM}		320	A			
V _T	16 A, T _J = 25 °C	1.25	V			
dV/dt		500	V/µs			
dl/dt		150	A/µs			
T _J		- 40 to 125	°C			

VOLTAGE RATINGS						
PART NUMBER	V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V _{DRM} , MAXIMUM PEAK DIRECT VOLTAGE V	I _{RRM} /I _{DRM} AT 125 °C mA			
VS-25TTS08PbF, VS-25TTS08-M3	800	800	10			
VS-25TTS12PbF, VS-25TTS12-M3	1200	1200	10			



VS-25TTS...PbF Series, VS-25TTS...-M3 Series

Vishay Semiconductors

ABSOLUTE MAXIMUM RATINGS									
DADAMETED	SYMBOL	TEST 001	NDITIONS	VALUES		LINUTO			
PARAMETER	SYMBOL TEST CONDITIONS		NUTTIONS	TYP.	MAX.	UNITS			
Maximum average on-state current	I _{T(AV)}	T _C = 93 °C, 180° conduc	tion half sine wave	1	6				
Maximum RMS on-state current	I _{RMS}			2	5	Α			
Maximum peak, one-cycle,	1	10 ms sine pulse, rated \	/ _{RRM} applied	27	70	^			
non-repetitive surge current	I _{TSM}	10 ms sine pulse, no volt	age reapplied	32	20				
Maximum I ² t for fusing	I ² t	10 ms sine pulse, rated V _{RRM} applied		36	65	A ² s			
Maximum i-t for fusing	I-I	10 ms sine pulse, no volt	age reapplied	5	15	A-S			
Maximum I ² √t for fusing	I ² √t	t = 0.1 to 10 ms, no volta	ge reapplied	51	52	A²√s			
Maximum on-state voltage drop	V_{TM}	16 A, T _J = 25 °C		1.5	25	٧			
On-state slope resistance	r _t	T _L = 125 °C		2.0	mΩ				
Threshold voltage	V _{T(TO)}	1,j = 125 C		.0	V				
Maximum various and divest leakage accurant	1 /1	T _J = 25 °C	V Dated V A/	0.	.5				
Maximum reverse and direct leakage current	I_{RM}/I_{DM}	T _J = 125 °C	$V_R = Rated V_{RRM}/V_{DRM}$	1	0				
Holding current	I _H	Anode supply = 6 V, resistive load, initial I_T = 1 A, T_J = 25 °C		-	150	mA			
Maximum latching current	ΙL	Anode supply = 6 V, resistive load, T _J = 25 °C			Anode supply = 6 V, resistive load, T _J = 25 °C		20	00	
Maximum rate of rise of off-state voltage	dV/dt	$T_J = T_J \text{ max., linear to } 80 ^{\circ}\text{C}, V_{DRM} = R_g - k = Open$			T _J = T _J max., linear to 80 °C, V _{DRM} = R _g - k = Open		50	00	V/µs
Maximum rate of rise of turned-on current	dl/dt				50	A/µs			

TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum peak gate power	P _{GM}		8.0	W	
Maximum average gate power	P _{G(AV)}		2.0	VV	
Maximum peak positive gate current	+ I _{GM}		1.5	Α	
Maximum peak negative gate voltage	- V _{GM}		10	V	
	I _{GT}	Anode supply = 6 V, resistive load, T _J = - 10 °C	60	mA	
Maximum required DC gate current to trigger		Anode supply = 6 V, resistive load, T _J = 25 °C	45		
		Anode supply = 6 V, resistive load, T _J = 125 °C	20		
		Anode supply = 6 V, resistive load, T _J = - 10 °C	2.5		
Maximum required DC gate voltage to trigger	V_{GT}	Anode supply = 6 V, resistive load, T _J = 25 °C	2.0	M	
voltage to trigger		Anode supply = 6 V, resistive load, T _J = 125 °C	1.0	V	
Maximum DC gate voltage not to trigger	$V_{\sf GD}$	T 105 °C V Detectively	0.25		
Maximum DC gate current not to trigger	I _{GD}	T _J = 125 °C, V _{DRM} = Rated value		mA	

SWITCHING					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Typical turn-on time	t _{gt}	T _J = 25 °C	0.9		
Typical reverse recovery time	t _{rr}	T _J = 125 °C	4	μs	
Typical turn-off time	t _q	1J = 125	110		



www.vishay.com

Vishay Semiconductors

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL	SYMBOL TEST CONDITIONS		UNITS
Maximum junction and storage temperature range		T_J , T_{Stg}		- 40 to 125	°C
Maximum thermal resistance, junction to case		R_{thJC}	DC operation	1.1	
Maximum thermal resistance, junction to ambient		R _{thJA}		62	°C/W
Typical thermal resistance, case to heatsink		R_{thCS}	Mounting surface, smooth and greased	0.5	
Approximate weight				2	g
Approximate weight				0.07	OZ.
Mounting torque -	minimum			6 (5)	kgf · cm
woulding torque	maximum			12 (10)	(lbf · in)
Marking device			Coop atula TO 220AP	25T	ΓS08
			Case style TO-220AB	25TTS12	

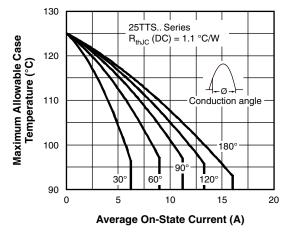


Fig. 1 - Current Rating Characteristics

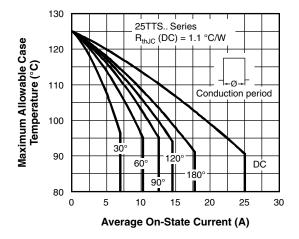


Fig. 2 - Current Rating Characteristics

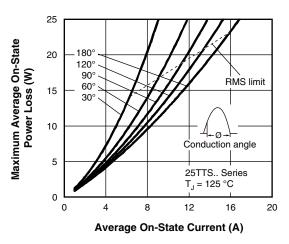


Fig. 3 - On-State Power Loss Characteristics

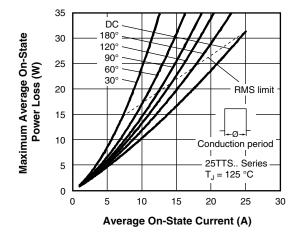


Fig. 4 - On-State Power Loss Characteristics

www.vishay.com

Vishay Semiconductors

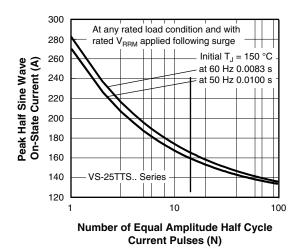


Fig. 5 - Maximum Non-Repetitive Surge Current

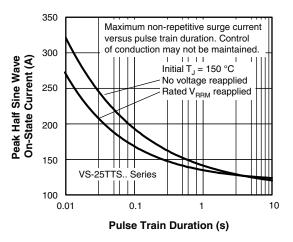


Fig. 6 - Maximum Non-Repetitive Surge Current

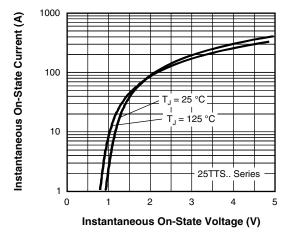


Fig. 7 - On-State Voltage Drop Characteristics

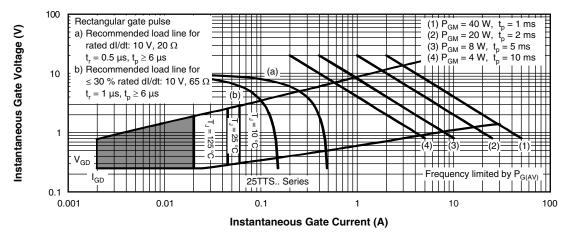


Fig. 8 - Gate Characteristics

VS-25TTS...PbF Series, VS-25TTS...-M3 Series

Vishay Semiconductors

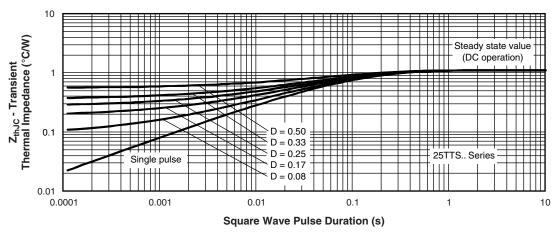
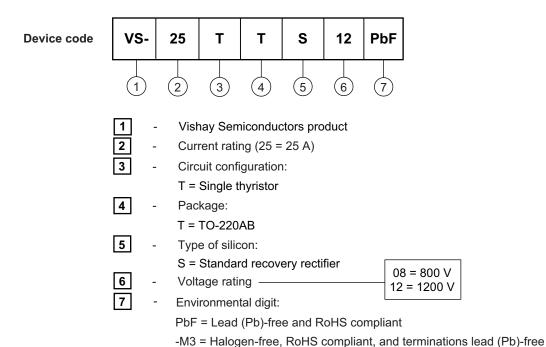


Fig. 9 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE



ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-25TTS08PbF	50	1000	Antistatic plastic tubes				
VS-25TTS08-M3	50	1000	Antistatic plastic tubes				
VS-25TTS12PbF	50	1000	Antistatic plastic tubes				
VS-25TTS12-M3	50	1000	Antistatic plastic tubes				

LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95222</u>				
Dort marking information	TO-220AB PbF	www.vishay.com/doc?95225		
Part marking information	TO-220AB -M3	www.vishay.com/doc?95028		



Vishay Semiconductors

TO-220AB

DIMENSIONS in millimeters and inches



Lead assignments

Diodes

- 1. Anode/open
- 2. Cathode
- 3. Anode

Conforms to JEDEC outline TO-220AB

SYMBOL	MILLIN	IETERS	INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6

SYMBOL	MILLIM	IETERS	INC	INCHES	
STIMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
E	10.11	10.51	0.398	0.414	3, 6
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
е	2.41	2.67	0.095	0.105	
e1	4.88	5.28	0.192	0.208	
H1	6.09	6.48	0.240	0.255	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØΡ	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	
θ	90° to 93°		90° t	o 93°	
		•	•	•	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimensions E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, except A2 (maximum) and D2 (minimum) where dimensions are derived from the actual package outline

Lead tip



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000